

# SEMICONDUCTOR MODELING

## For Simulating Signal, Power, and Electromagnetic Integrity

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Using the Companion CD-ROM	

**CD ROM**

This book comes with a CD that includes the following software and book information:

- *Sonnet<sup>®</sup> Lite from Sonnet Software, Inc.*
- *Visual IBIS Editor<sup>®</sup> from Mentor Graphics Corp.*

The CD-ROM also includes example data sheets, sample model files, IBIS syntax guides, presentations with practical model-building laboratory exercises (including input, intermediate, and output files), and other documentation. The appendixes on the CD include:

- Appendix A, Sample Data Sheets
- Appendix B, Sample IBIS Model Files
- Appendix C, Sample SPICE Models
- Appendix D, Sample S-Parameter Model
- Appendix E, Key Concepts of the IBIS Model
- Appendix F, List of Websites
- Appendix G, List of Software Providers
- Appendix H, Production Realities
- Appendix I, IBIS Quality Checklist
- Appendix J, Device Physics
- Appendix K, Logic Selection Guides
- Appendix L, Training Presentations